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## What is claimed is:

- 1. A method of fabricating a colossal magneto-resistive detector using a thin film transfer method, said method of fabricating comprising:
  - (a) growing a rock salt structure material layer on a perovskite oxide material substrate;
- (b) growing a protective layer comprising a lattice matched template material on said rock salt structure material layer;
  - (c) depositing a colossal magneto-resistive layer on said protective layer;
- (d) fabricating a detector array by adding contacts and processing devices to an interconnect surface of said colossal magneto-resistive layer;
  - (e) fabricating a bonded structure by bonding said detector array to a circuit;
- (f) removing said perovskite oxide material substrate from the rock salt structure material layer; and
  - (g) removing said rock salt structure material layer from the protective layer.
- 2. A method according to claim 1, wherein said perovskite oxide material substrate is a material selected from the group consisting of LaAlO<sub>3</sub> and SrTiO<sub>3</sub>.
- 3. A method according to claim 1, wherein said rock salt structure material substrate is a material selected from the group consisting of NaCl, LiF, NaF, KF, and KCl.

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- 4. A method according to claim 1, wherein said lattice matched template material is a colossal magneto-resistive material.
  - 5. A method according to claim 1, wherein said circuit is a readout integrated circuit.
  - 6. A method according to claim 1, wherein step (f) comprises an etching method.
- 7. A method according to claim 1, wherein step (g) comprises dissolving said rock salt structure material substrate in water, and said method further comprises:
  - (h) removing excess rock salt structure material/water solution.
- 8. A method according to claim 7, wherein step (h) is carried out by a water rinse and a method selected from the group consisting of evaporation, triple-point, and freeze drying.
- 9. A method according to claim 1, further comprising: removing said protective layer by etching.